

TSMC Certifies ANSYS Power Integrity And Electromigration Solutions For 10nm FinFET Early Design Start

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PITTSBURGH, April 6, 2015 /PRNewswire/ -- ANSYS, Inc. (NASDAQ: ANSS) announced today that its ANSYS® RedHawk™ and ANSYS Totem™ products are certified by TSMC for the most current version of 10-nanometer (nm) FinFET Design Rule Manual (DRM) and SPICE models, addressing the power and performance requirements for mobile, computing and networking applications. TSMC has certified these solutions for static and dynamic voltage drop analysis and advanced signal and power electromigration (EM) verification to meet the 10-nanometer requirements.



Complex device structure and high drive currents in FinFET devices make power integrity and EM key design requirements. With innovative algorithms and analysis engines, ANSYS solutions deliver needed accuracy while reducing turnaround time to meet the increased computational requirements caused by modern products' growing design complexity. Advanced technology support in RedHawk and Totem, including EM rule compliance and color-aware resistance extraction, help deliver greater reliability and manufacturability.

"The certification of RedHawk and Totem for 10nm FinFET technology ensures our products' ability to deliver the accuracy required for power and advanced EM sign-off," said Fares Mubarak, vice president and general manager of ANSYS. "By continuously collaborating with TSMC, we are able to provide optimized tools and methodologies for the industry's most advanced process nodes and the customers using them in their emerging design technologies."

"TSMC and ANSYS collaborate closely on 10nm FinFET EM/IR tool certification for early adopters to ensure more robust and reliable system-on-chips for next-generation electronic products," said Suk Lee, TSMC senior director, Design Infrastructure Marketing Division.

The ANSYS portfolio of product offerings will be showcased at the upcoming TSMC Technology Symposium in San Jose, California; Austin, Texas and Boston, as well as at <u>Design Automation Conference</u> (DAC) in exhibit booth #1232.

About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs over 2700 professionals, many of them experts in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansys.com/Social@ANSYS

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Contact	Media	Tom Smithyman
		724.514.3076
		tom.smithyman@ansys.com
	Investors	Annette Arribas
		724.514.1782
		annette.arribas@ansys.com

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